

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
SHIU, HEI MING

Application No.: 10/731831

Filed: 12-09-2003

Title: METHOD OF FORMING LAND GRID ARRAY PACKAGED DEVICE

§ Patent No.: 7056766 B2
§
§ Issue Date: 4/4/2006
§
§ Examiner: Evan Pert
§
§ Group Art Unit: 2826
§
§ Docket No.: SC13152HP
§

Certificate of Submission

I hereby certify that this correspondence is being submitted to the USPTO, Alexandria, VA.

- ☐ Addressed per C.F.R. § 1.1(a) and deposited with the United States Postal Service with sufficient postage as first class mail.
- ☐ Facsimile transmitted in accordance with C.F.R. §1.6(d).
- ☒ Submitted electronically via EFS in accordance with "Legal Framework for EFS Web".

February 12, 2008
Date of Submission

/Teresa Shephard/
Signature

Teresa Shephard
Printed Name of Person Signing Certificate

Commissioner for Patents
Alexandria, VA 22313

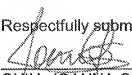
SUBMISSION OF CERTIFICATE OF CORRECTION

Dear Commissioner:

Enclosed is a Certificate of Correction listing error(s) in the subject patent. Please enter these corrections. Since the error(s) appear to be on the part of the Applicant, the required fee will be charged to Deposit Account 503079 via the Electronic Filing System.

2/11/08
Date

Respectfully submitted,


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CERTIFICATE OF CORRECTION

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PATENT NO.: 7056766 B2
APPLICATION NO: 10/731831
DATE: 12-09-2003
FIRST NAMED INVENTOR: SHIU, HEI MING

It is certified that error appears in the above-identified patent and that said Letters Patent are hereby corrected as shown below:

In Column 7, Line 11, Claim No. 14:

Change "dice, comprising" to -die, comprising--

In Column 7, Line 18, Claim No. 14:

Change "dice to the mold" to -die to the mold--

In Column 7, Line 19, Claim No. 14:

Change "of the dice have" to -of the die have--

In Column 7, Line 22, Claim No. 14:

Change "of the dice to" to -of the die to--

In Column 7, Line 24, Claim No. 14:

Change "dice;" to -die;--

In Column 7, Line 25, Claim No. 14:

Change "encapsulating the dice," to -encapsulating the die,--

In Column 7, Line 28, Claim No. 14:

Change "such that a bottom" to -such that bottom--

In Column 7, Line 30, Claim No. 14:

Change "encapsulated dice to" to -encapsulated die to--

In Column 8, Line 14, Claim No. 20:

Change "wherein the dice" to -wherein the die--

In Column 8, Line 15, Claim No. 20:

Change "side of the dice" to -side of the die--

MAILING ADDRESS OF SENDER (Please do not use customer number below)

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